

L Number	Hits	Search Text	DB	Time stamp
1	3106	324/754.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:53
2	747	324/758.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:53
3	3027	324/765.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:53
4	6438	324/754.ccls. or 324/758.ccls. or 324/765.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:55
5	669	(automated and camera and (contact adj3 surface) and alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:04
6	15	(324/754.ccls. or 324/758.ccls. or 324/765.ccls.) and ((automated and camera and (contact adj3 surface) and alignment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 14:57
7	3048	( camera and (contact adj3 surface) and alignment)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:05
8	56	(324/754.ccls. or 324/758.ccls. or 324/765.ccls.) and (( camera and (contact adj3 surface) and alignment))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:23
9	286	324/758.cor.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:40
10	219	324/754.ccls. and 324/758.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/12 15:40
-	166804	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:18
-	53138	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:19
-	9052	((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested ) and (semiconductor or circuit or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:21

-	1115	((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested ) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:22
-	267	((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested ) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)) and (image and (defect or flaw))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:24
-	204	((((removing or removed or subtracting or subtracted or reducing or reduced)with substrate)) and (heat or temperture)) and (testing or test or tested ) and (semiconductor or circuit or chip)) and (liquid adj1 crystal)) and (image and (defect or flaw))) and (substrate with (removal or removed or removing))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/03 10:26